



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-02-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS2L40UF	7N6Y*Z73Q83Y	A	ZA41	2016-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
50.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.3 - 3.75 - 1	2	flat	
Comment	Package: SMB Flat NEP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7N6Y*Z73Q83Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.926	mg	supplier	die	Silicon (Si)	7440-21-3		1.597	mg	829180	31940
				supplier	metallization	Aluminium (Al)	7429-90-5		0.077	mg	39979	1540
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1038	40
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	1558	60
				supplier	metallization	Nickel (Ni)	7440-02-0		0.008	mg	4154	160
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	5711	220
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	519	20
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1558	60
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.013	mg	6750	260
				supplier	polymer die coating	Durimide	proprietary		0.211	mg	109553	4220
Lead-frame & Clip	Copper & its alloys	23.926	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		23.895	mg	998704	477900
				Supplier	Alloy	Iron (Fe)	7439-89-6		0.024	mg	1003	480
Die Attach	Solder	2.744	mg	Supplier	Alloy	Phosphorus (P)	12185-10-3		0.007	mg	293	140
				Supplier	soft solder	Silver (Ag)	7440-22-4		0.069	mg	25146	1380
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.137	mg	49927	2740
				Supplier	JIG - R	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.538	mg	924927	50760
Encapsulation	Other inorganic materials	20.542	mg	Supplier	Molding Compound	Silica , amorphous,fused	60676-86-0		17.043	mg	829666	340860
				Supplier	Molding Compound	Epoxy resin proprietare;resin unknown	29690-82-2		2.762	mg	134456	55240
				Supplier	Molding Compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.113	mg	5501	2260
				Supplier	Molding Compound	Silica, quartz	14808-60-7		0.511	mg	24876	10220
				Supplier	Molding Compound	Carbon black	1333-86-4		0.113	mg	5501	2260
Connections coating	Solder	0.862	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		0.862	mg	1000000	17240